



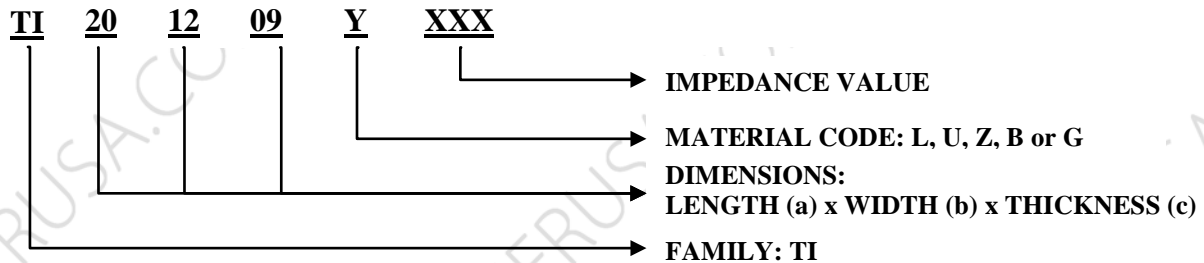
TI201209 (0805) Series SMD MULTILAYER FERRITE CHIP BEADS (HIGH CURRENT)

Rev. A

A. Electrical Specifications:

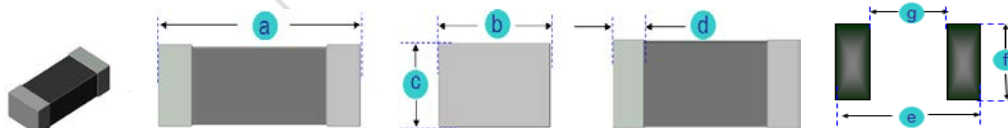
P/N	Impedance (Ω) $\pm 25\%$ @100MHz	DCR Max.(Ω)	I rms. Max.(A)
TI201209B070	7	0.010	6.0
TI201209G050	5	0.040	2.2
TI201209G070	7	0.040	2.2
TI201209G300	30	0.040	3.0
TI201209G600	60	0.040	3.0
TI201209G800	80	0.060	3.0
TI201209G121	120	0.080	3.0
TI201209G151	150	0.080	3.0
TI201209G221	220	0.100	2.5
TI201209G301	300	0.100	2.5
TI201209G601	600	0.150	2.0
TI201209U070	7	0.010	6.0
TI201209U100	10	0.010	6.0
TI201209U110	11	0.010	6.0
TI201209U150	15	0.025	3.0
TI201209U170	17	0.025	4.0
TI201209U200	20	0.010	6.0
TI201209U260	26	0.020	5.0
TI201209U300	30	0.010	6.0
TI201209U310	31	0.010	6.0
TI201209U400	40	0.025	4.0
TI201209U470	47	0.050	3.0
TI201209U600	60	0.050	3.0
TI201209U700	70	0.060	3.0
TI201209U800	80	0.060	3.0
TI201209U101	100	0.040	4.0
TI201209U121	120	0.040	4.0
TI201209U151	150	0.060	3.0
TI201209U181	180	0.080	3.0
TI201209U221	220	0.080	3.0
TI201209U301	300	0.100	2.5
TI201209U471	470	0.150	2.0
TI201209U601	600	0.150	2.0
TI201209U102	1000	0.300	1.0
TI201209Z110	11	0.010	6.0
TI201209Z300	30	0.020	5.0
TI201209Z600	60	0.020	5.0
TI201209Z800	80	0.030	5.0
TI201209Z121	120	0.060	3.0
TI201209Z181	180	0.080	3.0
TI201209Z221	220	0.080	3.0
TI201209Z301	300	0.100	2.0
TI201209Z601	600	0.150	2.0
TI201209Z102	1000	0.300	1.0

B. Part Number Key:



C. Dimensions: mm (Inch)

Series	a	b	c	d	e	f	g
TI201209(0805)	2.0 (0.079)	1.2 (0.047)	0.9 (0.035)	0.5 (0.020)	3.20 (0.126)	1.50 (0.059)	0.60 (0.024)
Tol.	± 0.2 (0.008)	± 0.2 (0.008)	± 0.2 (0.008)	± 0.3 (0.012)	Typ.	Typ.	Typ.





TI201209 (0805) Series
SMD MULTILAYER FERRITE CHIP BEADS (HIGH CURRENT)

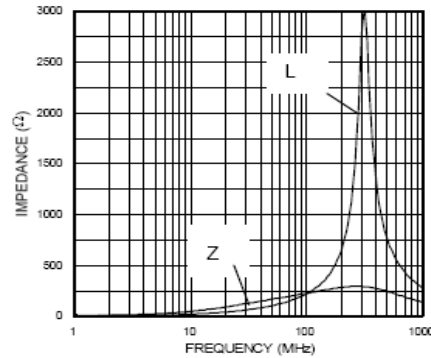
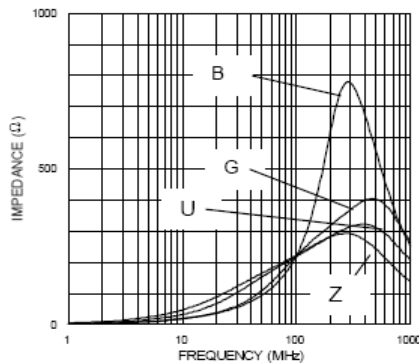
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D. Materials:

ITEM	UNIT	Material Code				
		L	B	G	U	Z
Initial Permeability (μ_{iac}):	----	25	45	110	200	500
Maximum Permeability (μ_m):	----	125	125	250	450	900
Saturation Flux Density at 10 Oe:	Gauss	2000	2000	1700	1400	1500
Curie Temperature(T_c):	$^{\circ}C$	>200	>200	>130	>100	>130
Volume Resistivity (ρ):	$\Omega\text{-m}$	100000	100000	100000	100000	100000
Temperature Coefficient:	1/10000 $^{\circ}C$	10	10	13	5	12
Density:	g/cm 3	4.8	4.8	4.8	4.8	4.8

E. Impedance Characteristics of Materials:

- Z Material is for applications whose blocking regions are near 100 MHz.
- L Material, an improvement of B Material has sharp impedance characteristic at high frequency.
- G Material is for application whose signal frequency is far from the cut off region. Suitable for application requires low insertion loss at high frequency.
- Different materials are available for different application range.
- With one material, higher impedance has sharper characteristics.
- Please confirm the signal wave form to choose suitable products.



F. General Information:

- TI201209-yxxx, “TI” = Type, “20” = Length, “12” = Width, “09” = Thickness, “y” = Material, “xxx”= Impedance.
- Tolerance: $\pm 25\%$
- Small and lightweight surface mounting type
- High-density packaging with a pitch of 2.54 mm (0.1 inch) max. is possible. This series requires less space and have greater EMI suppression effects.
- Excellent in physical properties, such as terminal strength, flexure strength, soldering resistance and solder-ability.
- Applicable to both flow and IR reflow soldering.
- High impedance covers wide frequency ranges.
- TI series can be used in high current circuits due to its low DC resistance.
- Operating temperature: $-40^{\circ}C$ to $+125^{\circ}C$
- Impedance and Current range: From 5 Ω (2200 mA) to 1000 Ω (1000 mA)
- Unspecified values available on request.
- MSL: Level 1.

G. Applications:

- Game Consoles
- Set Top Boxes
- Cables Modems
- Computers
- Mobile Communication Devices (Cell Phones, Radios, etc.)